

Title (en)

PLASTIC ENCAPSULATED INTEGRATED CIRCUIT PACKAGE WITH FULLY SLOTTED DAMBAR

Title (de)

KUNSTSTOFFVERKAPSELTE INTEGRIERTE SCHALTUNGSVERPACKUNG MIT GENIETETER SPERRDICHTUNG

Title (fr)

BOITIER DE CIRCUIT INTEGRE ENCAPSULE DANS DU PLASTIQUE DOTE DE BARRIERE ENTIEREMENT FENDUE

Publication

EP 0692143 A1 19960117 (EN)

Application

EP 94911707 A 19940324

Priority

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Abstract (en)

[origin: WO9423452A1] A plastic encapsulated integrated circuit package is disclosed herein. This IC package (24) includes a lead frame (12) having an IC attachment pad, a lead chip, or other suitable means (14) for supporting an IC chip, a plastic molding encapsulating (26) the IC pad and chip (16), and spaced-apart but adjacent electrically conductive leads (28) forming part of the lead frame and extending out from the plastic molding (26). The lead frame also includes an electrically conductive dambar (30) extending across the leads (28) at points adjacent to and just outside the plastic molding (26). This particular dambar (30), as disclosed, includes initially formed through-slots (32) between adjacent ones of the leads (28), that is, through-slots (32) that are provided before the package is encapsulated with plastic. This through-slotted dambar (30) is especially designed for use with a fine pitched IC package and functions in the normal plastic damming manner, notwithstanding its through-slots (32) which are sufficiently large to receive the following plastic as the package is encapsulated but small enough to prevent the plastic from flowing beyond the dambar (30).

IPC 1-7

H01L 23/495

IPC 8 full level

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